

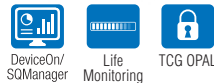
SQF-C8M ER-1

PCIe Gen.4 x4 M.2 2280 SSD



Features

- NGFF M.2 2280 (M Key)
- Compliant with NVMe 1.4
- AES-256 Support & TCG-OPAL Compliant
- Supports LDPC & RAID ECC
- Read-Intensive and Mixed-Use support
- Heat-spreading design with thermal solution
- SMART and GUI management tool



Specifications

Connect Type	NGFF M Key
Flash type	3D TLC
Capacity	400GB ~ 3.2TB
Transfer Mode	PCIe Gen.4 x4
Max. Power Consumption	Read: 7.3 W, Write: 6.1 W
Sequential R/W Performance (*)	up to 6,500/ 5,000 MB/sec
Random R/W IOPS (*)	up to 779K/ 753K
Endurance (DWPD)	Read-Intensive: DWPD 1 Mixed-Use: DWPD 3
Operating Temperature	Commercial grade: 0 to +70 °C Industrial grade: -40 to +85 °C
Shock Resistance	1,500 G, peak / 0.5 ms
Vibration Resistance	20 G, peak / 80 ~ 2000 Hz
Dimensions (mm)	80.4 x 23.3 x 20.5

(*) These values are for reference only; they may change according to the flash memory used.

Ordering Information

PN	Description
SQF-C8MV4-400GDG1C	SQF PCIe/NVMe M.2 2280 ER-1 400G 3D TLC, DWPD 1 (0 ~ 70 °C)
SQF-C8MV4-800GDG1C	SQF PCIe/NVMe M.2 2280 ER-1 800G 3D TLC DWPD 1 (0 ~ 70 °C)
SQF-C8MV4-1K6GDG1C	SQF PCIe/NVMe M.2 2280 ER-1 1600G 3D TLC DWPD 1 (0 ~ 70 °C)
SQF-C8MV4-3K2GDG1C	SQF PCIe/NVMe M.2 2280 ER-1 3200G 3D TLC DWPD 1 (0 ~ 70 °C)
SQF-C8MV4-400GDG1E	SQF PCIe/NVMe M.2 2280 ER-1 400G 3D TLC DWPD 1 (-40 ~ 85 °C)
SQF-C8MV4-800GDG1E	SQF PCIe/NVMe M.2 2280 ER-1 800G 3D TLC DWPD 1 (-40 ~ 85 °C)
SQF-C8MV4-1K6GDG1E	SQF PCIe/NVMe M.2 2280 ER-1 1600G 3D TLC DWPD 1 (-40 ~ 85 °C)
SQF-C8MV4-3K2GDG1E	SQF PCIe/NVMe M.2 2280 ER-1 3200G 3D TLC DWPD 1 (-40 ~ 85 °C)
SQF-C8MF4C400GDG1C	SQF PCIe/NVMe M.2 2280 ER-1 400G 3D TLC DWPD 3 (0 ~ 70 °C)
SQF-C8MF4C800GDG1C	SQF PCIe/NVMe M.2 2280 ER-1 800G 3D TLC DWPD 3 (0 ~ 70 °C)
SQF-C8MF4C1K6GDG1C	SQF PCIe/NVMe M.2 2280 ER-1 1600G 3D TLC DWPD 3 (0 ~ 70 °C)
SQF-C8MF4C3K2GDG1C	SQF PCIe/NVMe M.2 2280 ER-1 3200G 3D TLC DWPD 3 (0 ~ 70 °C)